

REMARKS

This responds to the Office Action dated on May 16, 2005.

Claims 1, 4, 27, 34, 40, 41, and 42 are amended, no claims are canceled, and no claims are added; as a result, claims 1-58 are now pending in this application with claims 1-9 and 27-45 currently pending examination. The amendments to the claims are fully supported by the specification as originally filed. No new matter is introduced. Applicant respectfully requests reconsideration of the above-identified application in view of the amendments above and the remarks that follow.

Support for claims 1, 4, 40, and 41 may be found in the specification, for example, on page 9, line 24 – page 10, line 6. Support for claim 42 may be found in the specification, for example, on page 10, lines 28-29 and page 11, lines 3-5. Claims 27 and 34 are amended to clarify these claims.

Information Disclosure Statement

Applicant submitted an Information Disclosure Statement and a 1449 Form on November 26, 2003. Applicant respectfully requests that initialed copies of the 1449 Forms be returned to Applicant's Representatives to indicate that the cited references have been considered by the Examiner.

§102 Rejection of the Claims

Claims 1-4, 6, 8, 9, 27-36, and 39 were rejected under 35 U.S.C. § 102(e) as being anticipated by Yang (U.S. Patent No. 6,498,387). Applicant traverses these grounds of rejection of these claims.

Applicant reserves the right to swear behind Yang at a later date.

Applicant cannot find in Yang a disclosure, a teaching, or a suggestion of a method including applying an adhesive to a first side of a finished wafer, the adhesive being one or more of an elastomer applied in fluid form, a thermoplastic material, or a pressure-sensitive film, as recited in amended claim 1. Applicant submits that Yang does not disclose, teach, or suggest all the elements of claim 1 and Yang does not disclose, teach, or suggest the identical invention in as complete detail as is contained in claim 1. Therefore, Applicant submits that Yang does not anticipate claim 1. Thus, Applicant submits that claim 1 is patentable over Yang. Claims 2-3

depend from claim 1 and are patentable over Yang for at least the reasons discussed above with respect to claim 1.

Applicant cannot find in Yang a disclosure, a teaching, or a suggestion of a method including applying an adhesive to a first side of a finished wafer, the adhesive being an elastomer applied in fluid form, as recited in amended claim 4. Applicant submits that Yang does not disclose, teach, or suggest all the elements of claim 4 and that Yang does not disclose, teach, or suggest the identical invention in as complete detail as is contained in claim 4. Therefore, Applicant submits that Yang does not anticipate claim 4. Thus, Applicant submits that claim 4 is patentable over Yang. Claims 6, 8, and 9 depend from claim 4 and are patentable over Yang for at least the reasons discussed above with respect to claim 4.

Claim 27 is amended to clarify the claim. Applicant cannot find in Yang a disclosure, a teaching, or a suggestion of a method including applying an adhesive layer to a first side of a finished wafer after forming an array of conductive elements within the adhesive layer as recited in claim 27. In contrast, Yang forms a “pad circuit 17” over an epoxy after applying the epoxy to a wafer. *See, Yang column 3, line 65 – column 4, line 14.* Applicant submits that Yang does not disclose, teach, or suggest all the elements as arranged in claim 27 and Yang does not disclose, teach, or suggest the identical invention in as complete detail as is contained in claim 27. Therefore, Applicant submits that Yang does not anticipate claim 27. Thus, Applicant submits that claim 27 is patentable over Yang. Claims 28-33 depend from claim 27 and are patentable over Yang for at least the reasons discussed above with respect to claim 27.

Claim 34 is amended to clarify the claim. Applicant cannot find in Yang a disclosure, a teaching, or a suggestion of a method including applying an adhesive layer to a first side of a finished wafer after coupling an array of conductive elements to an array of connection pads on a die, forming an array of conductive elements within the adhesive later as recited in claim 34. In contrast, Yang forms a “pad circuit 17” over an epoxy after applying the epoxy to a wafer. *See, Yang column 3, line 65 – column 4, line 14.* Applicant submits that Yang does not disclose, teach, or suggest all the elements as arranged in claim 34 and Yang does not disclose, teach, or suggest the identical invention in as complete detail as is contained in claim 34. Therefore, Applicant submits that Yang does not anticipate claim 34. Thus, Applicant submits that claim 34

is patentable over Yang. Claims 35, 36, and 39 depend from claim 34 and are patentable over Yang for at least the reasons discussed above with respect to claim 34.

Applicant respectfully requests withdrawal of these rejections of claims 1-4, 6, 8, 9, 27-36, and 39, and reconsideration and allowance of these claims.

First §103 Rejection of the Claims

Claims 5, 40-43, and 45 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Yang (U.S. Patent No. 6,498,387) in combination with Elenius et al. (U.S. Patent No. 6,441,487). Applicant traverses these grounds of rejection of these claims.

Applicant reserves the right to swear behind Elenius et al. (hereafter Elenius) at a later date.

Applicant cannot find in the combination of Yang and Elenius, as proposed in the Office Action, a teaching or a suggestion of a method including applying an adhesive to a first side of a finished wafer, the adhesive being an elastomer applied in fluid form, as recited in amended claim 4. Thus, Applicant submits that Yang does not teach or suggest all the elements of claim 4 and, therefore, claim 4 is patentable over Yang in combination with Elenius. Claim 5 depends on claim 4 and is patentable over Yang in combination with Elenius for at least the reasons stated above.

Applicant cannot find in the combination of Yang and Elenius, as proposed in the Office Action, a teaching or a suggestion of a method including applying an adhesive layer to a first side of a finished wafer, the adhesive layer being a thermoplastic material, as recited in amended claim 40. Thus, Applicant submits that Yang does not teach or suggest all the elements of claim 40 and, therefore, claim 40 is patentable over Yang in combination with Elenius. Claims 40-43 depend on claim 40 and are patentable over Yang in combination with Elenius for at least the reasons stated above.

Applicant respectfully requests withdrawal of these rejections of claims 5, 40-43, and 45, and reconsideration and allowance of these claims.

Second §103 Rejection of the Claims

Claim 7 was rejected under 35 U.S.C. § 103(a) as being unpatentable over Yang (U.S. Patent No. 6,498,387) in combination with Moriya et al. (U.S. Patent No. 6,013,944). Applicant traverses these grounds of rejection of these claims.

Applicant cannot find in the combination of Yang and Moriya et al. (hereafter Moriya), as proposed in the Office Action, a teaching or a suggestion of a method including applying an adhesive to a first side of a finished wafer, the adhesive being an elastomer applied in fluid form, as recited in amended claim 4. Thus, Applicant submits that the combination of Yang and Moriya does not teach or suggest all the elements of claim 4 and that claim 4 is patentable over the combination of Yang and Moriya. Claim 7 depends from claim 4 and is patentable over the combination of Yang and Moriya for at least the reason stated above.

Applicant respectfully requests withdrawal of these rejections of claim 7, and reconsideration and allowance of this claim.

Objections to the Claims

Claims 37 and 38 were objected to as being dependent upon a rejected base claim, but were indicated to be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

Claim 37 depends on claim 34. As discussed above, Applicant submits that claim 34 is patentable and, therefore, claim 34 is patentable for at least the reasons stated above with respect to claim 34. Claim 38 depends on claim 37, and Applicant submits that claim 38 is therefore patentable.

The Office Action makes assertions regarding the interpretations of limitations of the claims, the contents of the art, and distinguishing features of the claims. Applicant has neither verified nor accepted the accuracy of these assertions, and respectfully submits that there may be different interpretations from those identified in the Office Action. Additionally, Applicant respectfully submits that the relevant claims may be allowable for one or more reasons in addition to and/or in alternative to those reasons identified in the Office Action. Applicant reserves the right to further address one or more aspects of these statements in the Office Action as may later be necessary or desirable.

Applicant respectfully requests the withdrawal of the objections to claims 37 and 38, and reconsideration and allowance of these claims.

Status of Claim 44

Applicant cannot find in the Office Action a rejection of dependent claim 44 on any grounds. However, Applicant also cannot find an objection to claim 44 in which claim 44 is objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims. Therefore, Applicant reserves the right to address the status of claim 44 at a later date including rewriting claim 44 in independent form including all of the limitations of the original base claim and any original intervening claims.

CONCLUSION

Applicant respectfully submits that the claims are in condition for allowance, and notification to that effect is earnestly requested. The Examiner is invited to telephone Applicant's attorney at (612) 371-2157 to facilitate prosecution of this application.

If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,

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By his Representatives,

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Date 16 August 2005

By _____



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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop Amendment, Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 16 day of August, 2005.

Name _____

Signature _____

Tina Kohut

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